

APPENDIX:

The Appendix includes the following item(s):

- ☒ - a new or amended Abstract of the Disclosure
- ☐ - a Replacement Sheet for Figure of the drawings
- ☐ - a Substitute Specification and a marked-up copy of the originally-filed specification
- ☐ - a terminal disclaimer
- ☐ - a 37 CFR 1.132 Declaration
- ☐ - a verified English translation of foreign priority document

ABSTRACT OF THE DISCLOSURE

Disclosed is a method for producing an HTSC band on a substrate band, for example, a strong bond being created between the substrate band and the band as a result of the production process (e.g. PVD process or galvanic deposition). According to the invention, separation of the highly adhesive band from the substrate band is aided by the fact that the substrate band is made of a shape memory alloy, the shape memory of the band being activated in a separating device by heating and, possibly, cooling. Tension-related stress is generated in the joint on the boundary surface between the bands as a result of the substrate being deformed such that separation of the band from the substrate band is aided or even caused. Also disclosed is a production facility in which the substrate band is made of a shape memory alloy.